

Request**PCB specification**

Date 23-02-22

Projectname: rsk_plus_rzt2m_ws2

PCB-No.: D017882_06

Rev.: 5

General requirements

IPC-A-600 G	Class II
RoHS compatible	Yes
UL-certification	Yes
Manufacturer logo	Yes
Date code	Yes
E-test	Yes
Impedance check	No
First sample test report	No
Grinding surface pattern	No
Position UL-No.and Logo	BOTTOM
Position manufacturer logo and Datecode	BOTTOM
Filled system	No

Production requirements

PCB-type:		rigid
PCB-dimension:	+/- 0,2 mm	150 x 150
Panel:		Not defined
Panel dimension:	+/- 0,2 mm	X x X
Piece per panel:		
Contour:		milled
PCB-thickness:	+/- 10% mm	1.49
Number of layers:		6
Inner layer copper incl. galv. Cu:	(µm)	35
External layer copper incl. galv. Cu:	(µm)	35
Smallest track width	(µm)	100
Smallest spacing width	(µm)	100
Material properties of surface:		chem. Ni/AU
Connectorgold:		No
Solder resist:		green
Silkscreen		Top/Bottom
Colour of silkscreen:		white
partial via print:		No
Carbon print:		No
Stripping paint:		No

Drill- and milling parameter

Smallest drill diameter (µm)	200
Number of drills per PCB (piece)	2336
Long holes	Yes
Edge contact	No
Backdrill	No
Blind via	No
Blind via / Drilling planes	
Buried via	No
Buried Via / drilling planes	
Microfill blind via	No
Plugging buried via	No
Milling tolerance, cut	Standard
level milling	No
Via technology	

Base material (on the basis of standard IPC-4101)

Material:	min. requirements		FR 4
TD:	>325, >345	° Celsius	>325
TG:		° Celsius	135
CTE Z axis (before TG, after TG)		ppm/k	<53 , <270
Permittivity (er)			3,7 - 4,5
T-260 / T-288		minutes	>60 / >15

Purchase

Invoice address:	Renesas Electronics Europe GmbH
	Arcadiastr. 10
	40472 Düsseldorf

Delivery address:	Renesas Electronics Europe GmbH
	Arcadiastr. 10
	40472 Düsseldorf

Single piece:	X
Panel piece:	
Delivery time:(working days)	15
Date of delivery:	xx.xx.2022

Ordering:**Technical:**

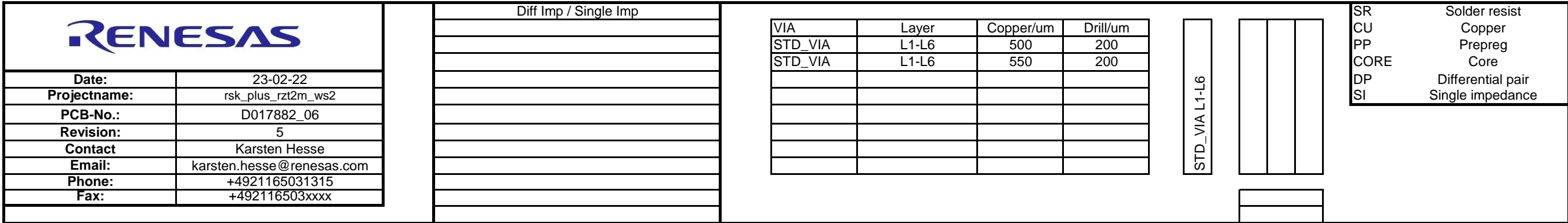
Contact:
 Email:
 Phone:
 Fax:




















Contact Person: Karsten Hesse
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Characteristics: Impedance designed PCB

Silkscreen print over vias: YES

Manufacturer logo and text pos. bottom!

[illegible]

-C21- [R3]	Component ID White
   	LPI Green -XV501T-4(STD)
	(1) CaC Foil 12um
	VT47 Prepreg 1080 (RC66)
	VT47 Prepreg 1080 (RC66)
	(2-3) VT47 0.180mm 35/35
	VT47 Prepreg 2116
	VT47 0.410mm 0/0
	VT47 Prepreg 2116
	(4-5) VT47 0.180mm 35/35
	VT47 Prepreg 1080 (RC66)
	VT47 Prepreg 1080 (RC66)
	(6) CaC Foil 12um
   	LPI Green -XV501T-4(STD)
-C21- [R3]	Component ID White